

MECHANICAL CASE OUTLINE

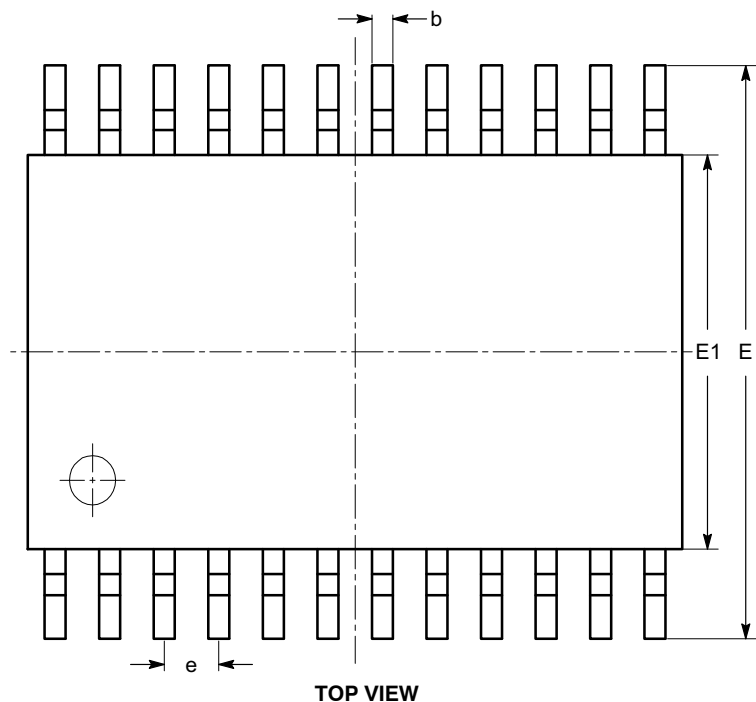
PACKAGE DIMENSIONS

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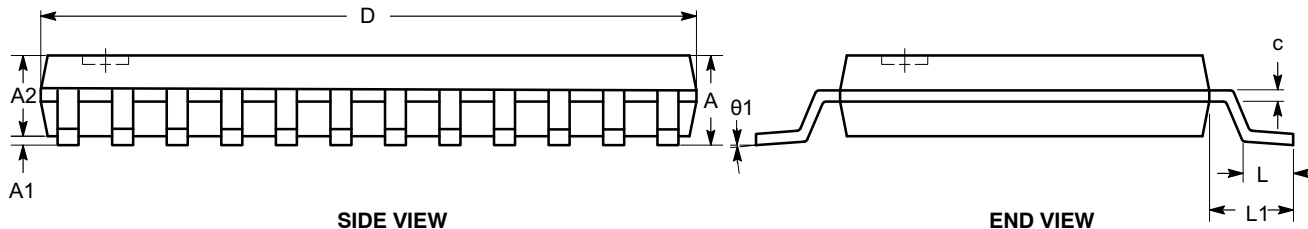


TSSOP24, 4.4x7.8
CASE 948AR-01
ISSUE A

DATE 17 MAR 2009



SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80		1.05
b	0.19		0.30
c	0.09		0.20
D	7.70	7.80	7.90
E	6.25	6.40	6.55
E1	4.30	4.40	4.50
e	0.65 BSC		
L	0.50	0.60	0.70
L1	1.00 REF		
θ	0°		8°



Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-153.

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